BGA416

RF Cascode Amplifier

Small Signal Discretes



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BGA416, RF Cascode Amplifier

Revision History: 2008-04-21, Rev. 2.1

Previous Version: 2005-07-26

Page	Subjects (major changes since last revision)			
All	Document layout change			
4-5	Electrical Characteristics slightly changed			
7-8	Figures updated			
-				

Trademarks

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Data Sheet 3 Rev. 2.1, 2008-04-21



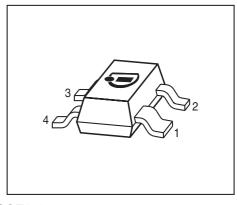
RF Cascode Amplifier

1 RF Cascode Amplifier

Feature

- G_{MA} = 23 dB at 900 MHz
- Ultra high reverse isolation, 60 dB at 900 MHz
- Low noise figure, $F_{50\Omega}$ = 1.2 dB at 900 MHz
- On chip bias circuitry, 5.5 mA bias current at $V_{\rm CC}$ = 3 V
- Typical supply voltage: 2.5 to 5.0 V
- SIEGET[®]-25 technology
- · Pb-free (RoHS compliant) package





SOT143

Applications

- · Buffer amplifier
- LNAs
- Oscillator active devices

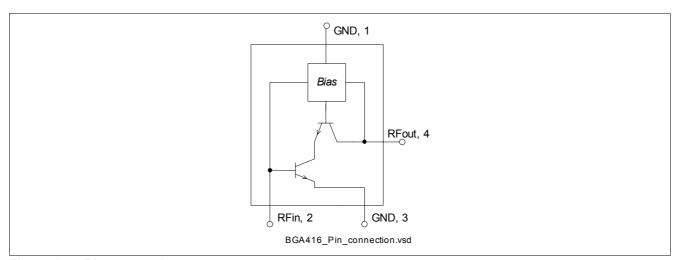


Figure 1 Pin connection

Description

BGA416 is a monolithic silicon cascode amplifier with high reverse isolation. A bias network is integrated for simplified biasing.

Туре	Package	Marking
BGA416	SOT143	C1s

Note: ESD: Electrostatic discharge sensitive device, observe handling precaution



Electrical Characteristics

Maximum Ratings

Table 1 Maximum ratings

Parameter	Symbol	Limit Value	Unit
Voltage at pin RFout	V_{OUT}	6	V
Device current ¹⁾	I_{D}	20	mA
Current into pin RFin	I_{in}	0.5	mA
Input power	P_{in}	8	dBm
Total power dissipation, $T_{\rm S}$ < 123°C ²⁾	P_{tot}	100	mW
Junction temperature	T_{J}	150	°C
Ambient temperature range	T_{A}	-65 150	°C
Storage temperature range	T_{STG}	-65 150	°C

¹⁾ Device current is equal to current into pin RFout

Note: All Voltages refer to GND-Node

Thermal resistance

Table 2 Thermal resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾	R_{thJS}	270	K/W

¹⁾ For calculation of R_{thJA} please refer to Application Note Thermal Resistance

2 Electrical Characteristics

Electrical characteristics at $T_{\rm A}$ = 25 °C (measured in test circuit specified in **Figure 2**) $V_{\rm CC}$ = 3 V, unless otherwise specified

Table 3 Electrical Characteristics

Parameter	Symbol	l Values		Unit	Note /	
		Min.	Тур.	Max.		Test Condition
Maximum available power gain	G_{MA}		23		dB	f = 0.9 GHz
			14		dB	f = 1.8 GHz
Insertion power gain	$ S_{21} ^2$		17		dB	f = 0.9 GHz
			11		dB	f = 1.8 GHz
Reverse isolation	$ S_{12} $		60		dB	f = 0.9 GHz
			40		dB	f = 1.8 GHz
Noise figure ($Z_{\rm S}$ = 50 Ω)	$F_{50\Omega}$		1.2		dB	f = 0.9 GHz
			1.6		dB	f = 1.8 GHz
Output power at 1 dB gain	$P_{ ext{-1dB}}$		-3		dBm	f = 0.9 GHz
compression ($Z_{\rm S}$ = $Z_{\rm L}$ = 50 Ω)			-3		dBm	f = 1.8 GHz
Output third order intercept point	OIP ₃		14		dBm	f = 0.9 GHz
$(Z_{\rm S}=Z_{\rm L}=50~\Omega)$			14		dBm	f = 1.8 GHz
Device current	I_{D}		5.5		mA	

²⁾ $T_{\rm S}$ is measured on the ground lead at the soldering point



Electrical Characteristics

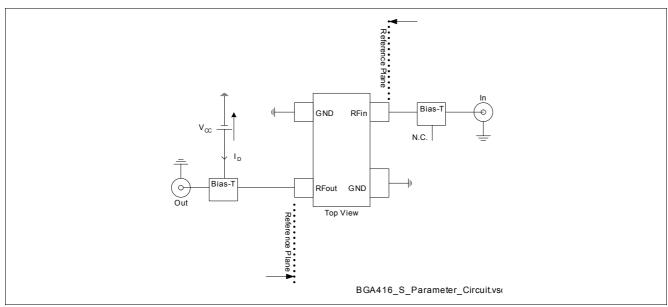


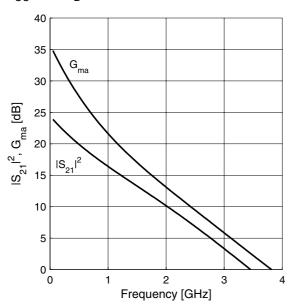
Figure 2 Test Circuit for Electrical Characteristics



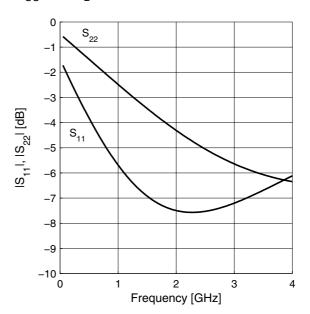
Measured Parameters

3 Measured Parameters

Power Gain
$$|S_{21}|^2$$
, $G_{ma} = f(f)$
 $V_{CC} = 3V$, $I_D = 5.5mA$

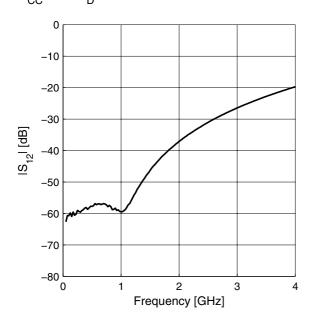


$$\begin{aligned} & \textbf{Matching} \ |S_{11}|, \ |S_{22}| = f(f) \\ & V_{CC} = 3V, \ I_D = 5.5 mA \end{aligned}$$



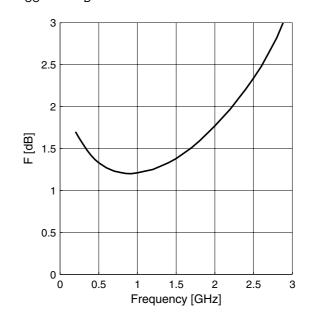
Reverse Isolation
$$|S_{12}| = f(f)$$

 $V_{CC} = 3V$, $I_D = 5.5mA$



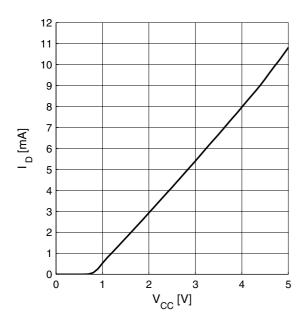
Noise figure
$$F = f(f)$$

$$V_{CC} = 3V, I_{D} = 5.5 \text{mA}$$



Package Information

Device Current $I_D = f(V_{CC})$



4 Package Information

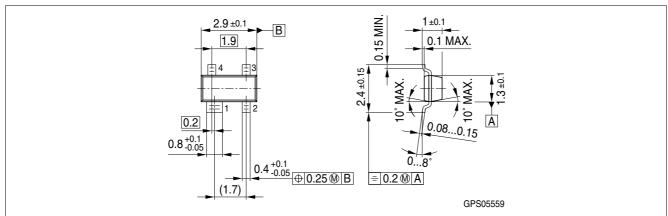


Figure 3 Package Outline SOT143

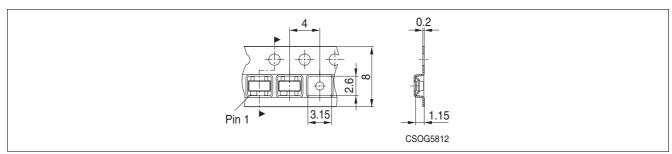


Figure 4 Tape for SOT143